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Kind regards,

Team Nexperia

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

Rev. 4 — 6 December 2011

Product data sheet

1. Product profile

1.1 General description

NPN/NPN double Resistor-Equipped Transistors (RET) in Surface-Mounted Device (SMD) plastic packages.

Table 1.	Product	overview
		0.0.0.0.0

Type number	Package		NPN/PNP PNP/PNP Package		U
	NXP	JEITA	complement	complement	configuration
PEMH13	SOT666	-	PEMD13	PEMB13	ultra small and flat lead
PUMH13	SOT363	SC-88	PUMD13	PUMB13	very small

1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design

1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

1.4 Quick reference data

Table 2.	Quick reference data					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per trans	istor					
V _{CEO}	collector-emitter voltage	open base	-	-	50	V
I _O	output current		-	-	100	mA
R1	bias resistor 1 (input)		3.3	4.7	6.1	kΩ
R2/R1	bias resistor ratio		8	10	12	



- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

| | 2 3 *sym063*

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

2. Pinning information

Table 3.	Pinning		
Pin	Description	Simplified outline	Graphic symbol
1	GND (emitter) TR1		
2	input (base) TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	output (collector) TR1	001aab555	

3. Ordering information

Table 4. Ordering information				
Type number	Package			
	Name	Description	Version	
PEMH13	-	plastic surface-mounted package; 6 leads	SOT666	
PUMH13	SC-88	plastic surface-mounted package; 6 leads	SOT363	

4. Marking

Table 5. Marking codes	
Type number	Marking code ^[1]
PEMH13	21
PUMH13	H0*

[1] * = placeholder for manufacturing site code

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

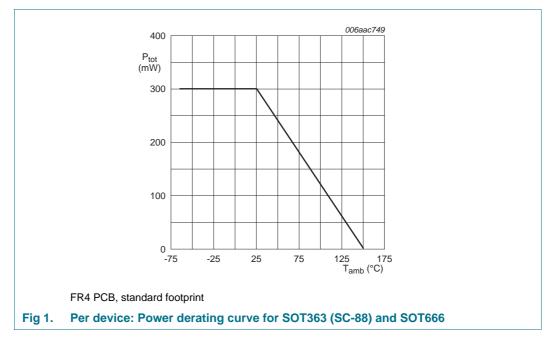
5. Limiting values

Symbol	Parameter	Conditions		Min	Max	Unit
Per transis	stor					
V _{CBO}	collector-base voltage	open emitter		-	50	V
V _{CEO}	collector-emitter voltage	open base		-	50	V
V _{EBO}	emitter-base voltage	open collector		-	5	V
VI	input voltage					
	positive			-	+30	V
	negative			-	-5	V
lo	output current			-	100	mA
I _{CM}	peak collector current	single pulse; t _p ≤ 1 ms		-	100	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$				
	PEMH13 (SOT666)		[1][2]	-	200	mW
	PUMH13 (SOT363)		<u>[1]</u>	-	200	mW
Per device	;					
P _{tot}	total power dissipation	$T_{amb} \leq 25 ~^{\circ}C$				
	PEMH13 (SOT666)		[1][2]	-	300	mW
	PUMH13 (SOT363)		<u>[1]</u>	-	300	mW
Tj	junction temperature			-	150	°C
T _{amb}	ambient temperature			-65	+150	°C
T _{stg}	storage temperature			-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω



Thermal characteristics 6.

<u> </u>	-	A 11/1		_		
Symbol	Parameter	Conditions	Mir	п Тур	Max	Unit
Per transi	istor					
R _{th(j-a)}	thermal resistance from junction to ambient	in free air				
	PEMH13 (SOT666)		<u>[1][2]</u>	-	625	K/W
	PUMH13 (SOT363)		<u>[1]</u> _	-	625	K/W
Per devic	e					
R _{th(j-a)}	thermal resistance from junction to ambient	in free air				
	PEMH13 (SOT666)		<u>[1][2]</u> _	-	417	K/W
	PUMH13 (SOT363)		<u>[1]</u> _	-	417	K/W

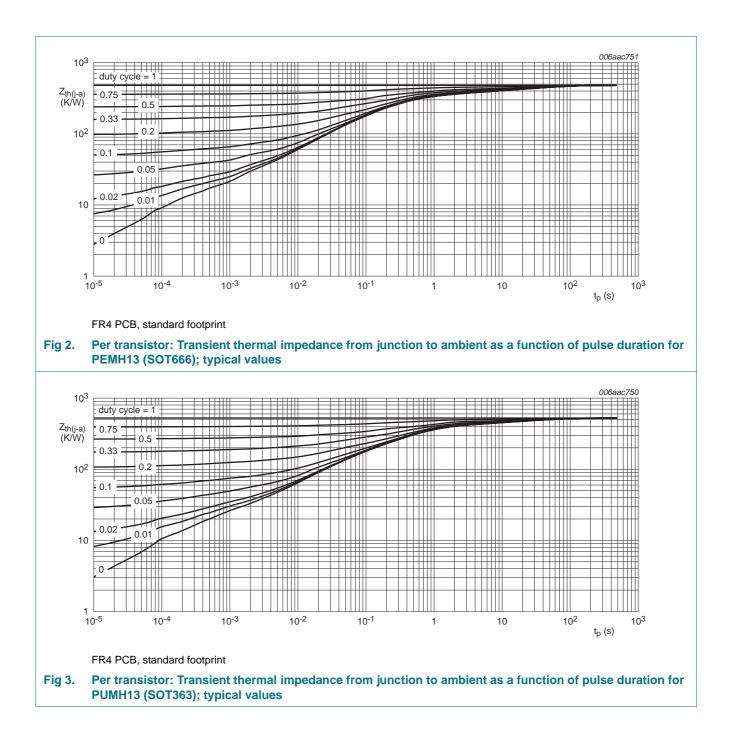
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

PEMH13_PUMH13

PEMH13; PUMH13

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω



7. Characteristics

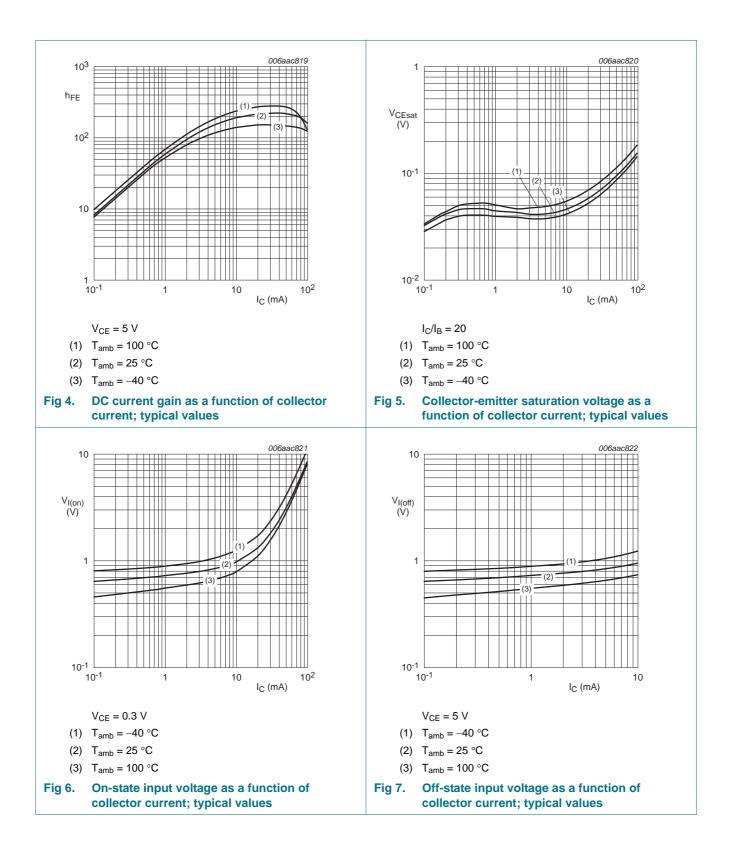
Table 8. $T_{amb} = 25$	Characteristics 5 °C unless otherwise spe	cified.				
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Per trans	sistor					
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; \text{ I}_{E} = 0 \text{ A}$	-	-	100	nA
I _{CEO}	collector-emitter cut-off	$V_{CE} = 30 \text{ V}; I_B = 0 \text{ A}$	-	-	1	μΑ
	current	$V_{CE} = 30 \text{ V}; I_B = 0 \text{ A};$ $T_j = 150 \text{ °C}$	-	-	5	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$	-	-	170	μA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 10 \text{ mA}$	100	-	-	
V _{CEsat}	collector-emitter saturation voltage	$I_{C} = 5 \text{ mA}; I_{B} = 0.25 \text{ mA}$	-	-	100	mV
V _{I(off)}	off-state input voltage	V_{CE} = 5 V; I_{C} = 100 μ A	-	0.6	0.5	V
V _{I(on)}	on-state input voltage	$V_{CE} = 0.3 \text{ V}; I_{C} = 5 \text{ mA}$	1.3	0.9	-	V
R1	bias resistor 1 (input)		3.3	4.7	6.1	kΩ
R2/R1	bias resistor ratio		8	10	12	
C _c	collector capacitance	$\label{eq:VCB} \begin{array}{l} V_{CB} = 10 \; V; I_E = i_e = 0 \; A; \\ f = 1 \; MHz \end{array}$	-	-	2.5	pF
f _T	transition frequency	$V_{CE} = 5 \text{ V}; I_{C} = 10 \text{ mA};$ f = 100 MHz	<u>[1]</u> _	230	-	MHz

[1] Characteristics of built-in transistor

PEMH13_PUMH13 Product data sheet

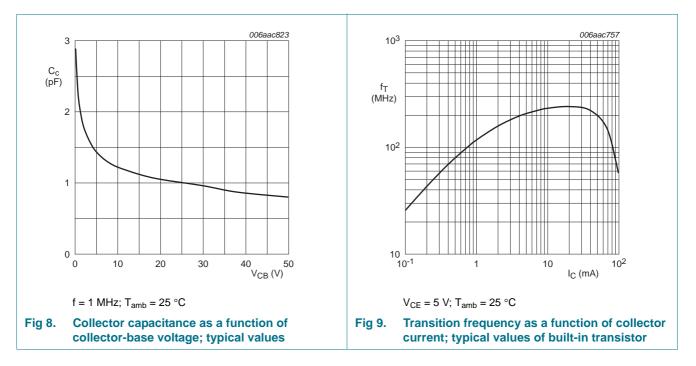
PEMH13; PUMH13

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω



PEMH13; PUMH13

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

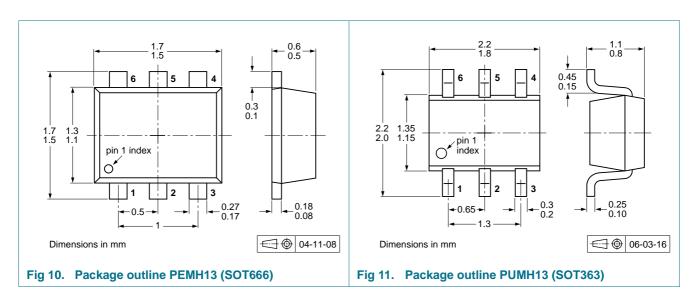


8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101* - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



PEMH13_PUMH13

10. Packing information

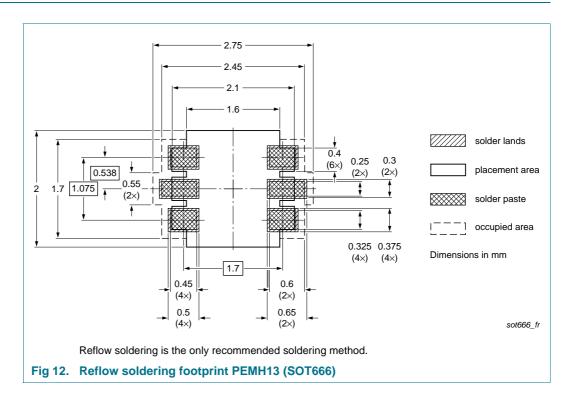
Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

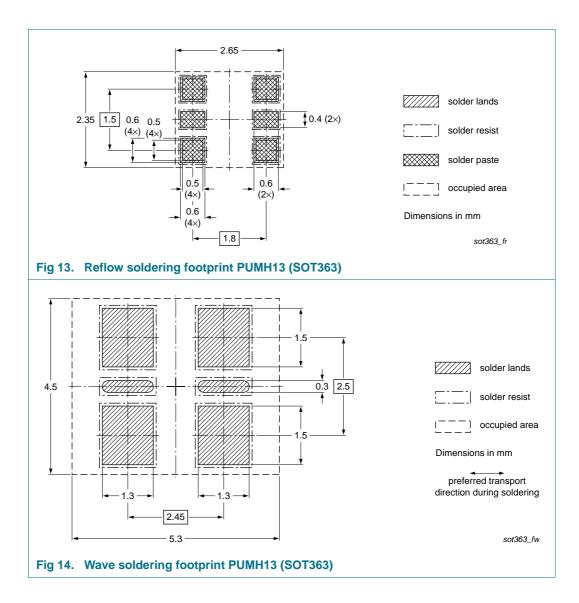
Туре	Package	Package Description			Packing quantity			
number				3000	4000	8000	10000	
PEMH13	SOT666	2 mm pitch, 8 mm tape and reel		-	-	-315	-	
		4 mm pitch, 8 mm tape and reel		-	-115	-	-	
PUMH13	SOT363	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-	-	-135	
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-	-	-165	

- [1] For further information and the availability of packing methods, see <u>Section 14</u>.
- [2] T1: normal taping
- [3] T2: reverse taping

11. Soldering



NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω



PEMH13_PUMH13
Product data shee

12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes		
PEMH13_PUMH13 v.4	20111206	Product data sheet	-	PEMH13_PUMH13 v.3		
Modifications:	 The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. 					
	• Legal texts have been adapted to the new company name where appropriate.					
	Section 1 "Product profile": updated					
	Section 4 "I	Marking": updated				
	• Figure 1 to 9: added					
	 <u>Section 5 "Limiting values"</u>: updated 					
	 <u>Section 6 "Thermal characteristics"</u>: updated 					
	 <u>Table 8 "Characteristics"</u>: V_{i(on)} redefined to V_{I(on)} on-state input voltage, V_{i(off)} redefined to V_{I(off)} off-state input voltage, I_{CEO} updated, f_T added 					
	<u>Section 8 "Test information"</u> : added					
	 <u>Section 9 "Package outline"</u>: superseded by minimized package outline drawing 					
	Section 10 "Packing information": added					
	 <u>Section 11 "Soldering"</u>: added 					
	Section 13	"Legal information": updated				
PEMH13_PUMH13 v.3	20040414	Product data sheet	-	PEMH13_PUMH13 v.2		
PEMH13_PUMH13 v.2	20031107	Product specification	-	PEMH13 v.1		
PEMH13 v.1	20011213	Preliminary specification	-	-		

PEMH13_PUMH13

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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PEMH13_PUMH13

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

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PEMH13; PUMH13

NPN/NPN resistor-equipped transistors; R1 = 4.7 k Ω , R2 = 47 k Ω

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